

Description

The AP90N06D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 60V I_D =90A

 $R_{DS(ON)}$ < 7.0m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

ackage Marking and Ordering information						
Product ID	Pack	Marking	Qty(PCS)			
AP90N06D	TO-252-3L	AP90N06D XXX YYYY	2500			

Absolute Maximum Ratings@T_i=25°C(unless otherwise specified)

Symbol	Parameter	Value	Unit
VDS	Drain source voltage	60	V
VGS	Gate source voltage	±20	V
ID	Continuous drain current ¹⁾	90	А
IDM	Pulsed drain current ²⁾	320	А
Is	Diode forward current	37	А
ISP	Pulsed source current	rce current 210	
P _D	Power dissipation	108	W
EAS	Single pulsed avalanche energy)	205.4	mJ
Tstg, Tj	Tstg, Tj Operation and storage temperature		°C
RθJC	RθJC Thermal resistance, junction-case		°C/W
RθJA	Thermal resistance, junction-ambient ⁴⁾	62	°C/W



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage V _{GS} =0V, I _D =250μA		60	68	-	٧
IDSS	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V,	-	1	1.0	μA
IGSS	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
RDS(on)	Static Drain-Source on-Resistance note	V _{GS} =10V, I _D =30A	-	5.3	7	mΩ
C _{iss}	Input Capacitance	.,	ı	4136	-	pF
Coss	Output Capacitance	V_{DS} =30V, V_{GS} =0V, f =1.0MHz	-	286	1	pF
Crss	Reverse Transfer Capacitance		-	257	1	pF
Qg	Total Gate Charge	V _{DS} =30V, I _D =30A,	-	90	-	nC
Q _{gs}	Gate-Source Charge	V _{GS} =10V	-	9	1	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	18	-	nC
td(on)	Turn-on Delay Time		1	9	1	ns
t _r	Turn-on Rise Time	V _{DS} =30V, I _D =30A,	1	7	ı	ns
td(off)	Turn-off Delay Time	$R_G=1.8\Omega$, $V_{GS}=10V$	-	40	-	ns
t _f	Turn-off Fall Time		1	15	1	ns
IS	Maximum Continuous Drain to Source Diode ForwardCurrent			ı	80	Α
ISM	Maximum Pulsed Drain to Source Diode Forward Current			1	320	Α
VSD	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	-	1	1.2	V
trr	Body Diode Reverse Recovery Time	1 004 11/11 4064/	-	33	1	ns
Qrr	Body Diode Reverse Recovery Charge	I _F =30A, dl/dt=100A/μs	-	46	-	nC



Electrical Characteristics Diagrams

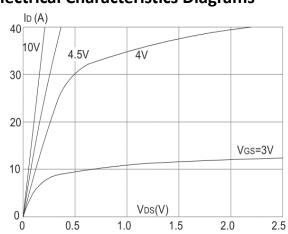


Figure1: Output Characteristics

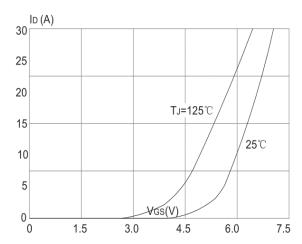


Figure 2: Typical Transfer Characteristics

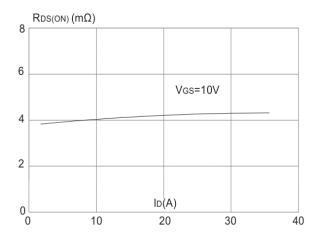


Figure 3:On-resistance vs. Drain Current

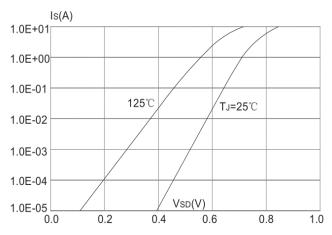


Figure 4: Body Diode Characteristics

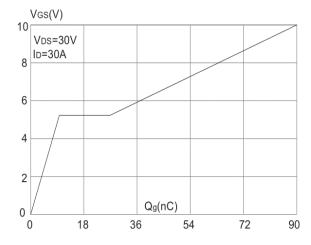


Figure 5: Gate Charge Characteristics

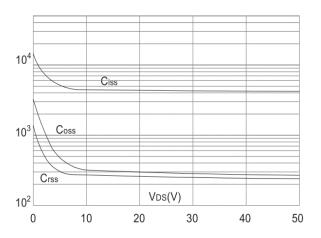


Figure 6: Capacitance Characteristics





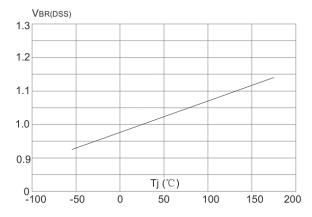


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

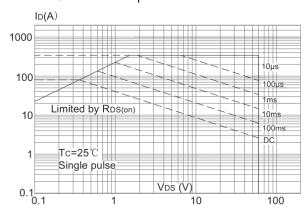


Figure 9: Maximum Safe Operating Area

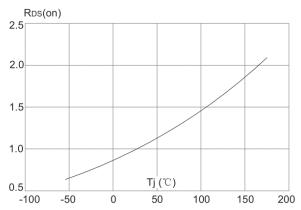


Figure 8: Normalized on Resistance vs. Junction Temperature

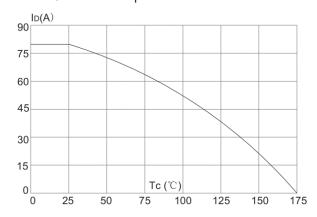


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

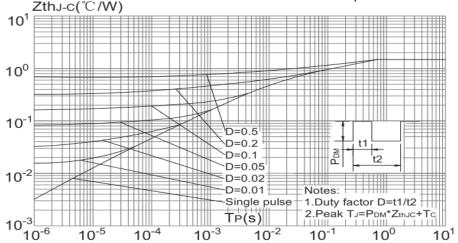
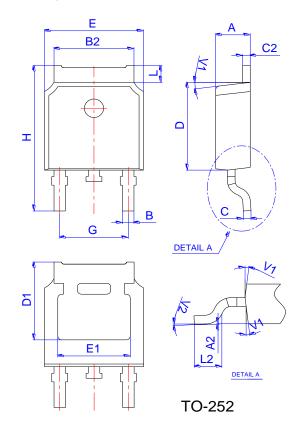


Figure.11: Maximum Effective
Transient Thermal Impedance, Junction-to-Case

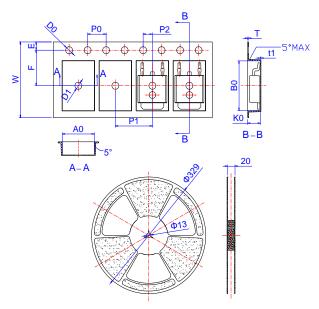


Package Mechanical Data



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Spectification-TO-252



	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
W	15.90	16.00	16.10	0.626	0.630	0.634	
E	1.65	1.75	1.85	0.065	0.069	0.073	
F	7.40	7.50	7.60	0.291	0.295	0.299	
D0	1.40	1.50	1.60	0.055	0.059	0.063	
D1	1.40	1.50	1.60	0.055	0.059	0.063	
P0	3.90	4.00	4.10	0.154	0.157	0.161	
P1	7.90	8.00	8.10	0.311	0.315	0.319	
P2	1.90	2.00	2.10	0.075	0.079	0.083	
A0	6.85	6.90	7.00	0.270	0.271	0.276	
В0	10.45	10.50	10.60	0.411	0.413	0.417	
K0	2.68	2.78	2.88	0.105	0.109	0.113	
Т	0.24		0.27	0.009		0.011	
t1	0.10			0.004			
10P0	39.80	40.00	40.20	1.567	1.575	1.583	





60V N-Channel Enhancement Mode MOSFET Attention

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AP90N06D

60V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2019/8/1	Initial release

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